

In the Specification

Please make the paragraph substitutions indicated in the appendix entitled Clean Version of Amended Specification Paragraphs. The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs:

The paragraph beginning at page 20, line 23, is amended as follows:

23 Figure 2C shows one embodiment of a method for fabricating an energy-
24 storage device. Steps 251, 253, 259, 261, and 263 are the substantially similar to
25 the steps described above with reference to Figure 2B. Step 255C is a step for
26 depositing a cathode film at least partially on the cathode contact film. In an
27 embodiment, the cathode film is deposited as described above in step 255. In other
28 embodiments, the cathode film is deposited according to other deposition processes
29 known in the art. The electrolyte film is formed by depositing an electrolyte
30 material to a location at least partially in contact with the cathode film (step ~~257B~~ 257C).

1 In a preferred embodiment, the electrolyte material is in contact with a substantial
2 portion of, if not all of, a surface of the cathode film. In some embodiments, an assist
3 source simultaneously supplies energized particles to the electrolyte material as it
4 forms the electrolyte film. In an embodiment, the assist source supplies a beam of
5 energized ions of an assist material different than the electrolyte material. In one
6 embodiment, the second material beam is directed to the same location on the
7 substrate as the electrolyte material. The energized ion beam assists in controlling
8 growth of the structure of the electrolyte film. The ion beam is unfocused in one
9 embodiment. The ion beam is ~~focussed~~ focused in another embodiment.

The paragraph beginning at page 27, line 18, is amended as follows:

18 Figure 7 shows another embodiment of a depositing apparatus 705 according
19 to the teachings of the present invention. Depositing apparatus 705 includes a
20 reaction chamber 707 in which is positioned an elongate, flexible substrate 709 on
21 which an energy-storage device is to be fabricated. The substrate 709 is fed from a
22 source roll 710 over an arched thermal control surface 715 and taken up by an end
23 roll ~~713~~ 718. A first material source 711 is provided in the chamber 707 and is a
24 physical deposition source. First source 711 produces a beam of adatoms 712 of a
25 material to be deposited on the substrate 709. In one embodiment, the first source
26 711 is an arc source including, for example, a cathodic arc source, an anodic arc
27 source, and a CAVAD arc source. In another embodiment, the first source 711 is a
28 physical vapor deposition source including, for example, a sputtering source. In
29 another embodiment, source 711 is a chemical vapor deposition source. Moreover,
30 source 711, in some embodiments, represents a plurality of different material

1 sources. Beam 712 is focused on a location 719 on the substrate 709 whereat the
2 adatoms in the beam are deposited to form a film layer of an energy-storage device.
3 An assist source 713 is provided in the chamber 707 and produces a beam of
4 energized particles 714 directed at the substrate 709. In an embodiment, the assist
5 source 713 produces a beam of energized ions 714. The energized particle beam
6 714 provides the energy required to control growth and stoichiometry of the
7 deposited material of the first beam 712. Thus, a crystalline structure is formed on
8 the substrate 709 as is explained in greater detail herein. The substrate 709, in one
9 embodiment, is an elastomer, polymer, or plastic web or sheet on which the energy-
10 storage device is fabricated. Substrate 709, being elongate, allows a plurality of
11 energy-storage devices to be deposited on successive locations of the substrate,
12 thereby improving the rate of energy device production. Moreover, a plurality of
13 deposition apparatuses 705 or sources 711, in some embodiments, are provided for
14 simultaneously depositing a plurality of films at different locations on the substrate
15 709.

The paragraph beginning at page 28, line 27, is amended as follows:

27 The above provides descriptions of various embodiments of systems in
28 which the present invention is performed to produce energy-storage devices or
29 energy-conversion devices. It is within the scope of the present invention to
30 combine the elements of the systems in different ways than shown and described as

1 long as the methods described herein are performable with such a system. For
2 example, in some embodiments, the flexible substrate 709 and rolls 710, ~~713~~ 718 can be
3 combined with any of the embodiments shown in Figures 3A-6. In some
4 embodiments, the thermal source 725 is also combinable with any of the
5 embodiments of Figures 3A-6. In some embodiments, the pivotable assist sources
6 413 are combinable with any of the embodiments of Figures 3A, 3B, 5A, 5B, and 7.
7 In some embodiments, the material sources 511A, 511B, and 511C are combinable
8 with embodiments of Figures 3A-5A and 6-7.

The paragraph beginning at page 29, line 9, is amended as follows:

9 In one embodiment, the electrode second film, e.g., films 59 or 71 is a
10 lithium-intercalation material which overlays at least part of the first film, e.g.,
11 contact films 57 or 63, but does not extend beyond the boundary of the first film.
12 Thus, the intercalation second film remains in a solid state during discharging and
13 charging of the energy-storage device. In some embodiments, the second film is
14 deposited using the first deposition source simultaneously with the secondary source
15 supplying energetic ions to the growing second film. In some embodiments, the
16 first deposition source is a physical vapor deposition source. In some embodiments,
17 the secondary source is an ion source supplying energetic ions from a source gas
18 comprising oxygen (e.g., O_2 O_2) or nitrogen (e.g., N_2 N_2). The source gas, in another
19 embodiment, comprises a noble gas, e.g., argon, xenon, helium, neon, and krypton.
20 The source gas, in yet another embodiment, comprises a hydrocarbon material such
21 as a hydrocarbon precursor. Selection of the secondary source gas is based on the
22 desired effect on the stoichiometry of the deposited film. The secondary source, in
23 one embodiment, provides a focused beam of energized ions. The secondary
24 source, in one embodiment, provides an unfocused beam of energized ions. The
25 energized ions provide energy to the lithium-intercalation material in the range of
26 about 5 eV to about 3,000 eV. In one embodiment, the energy range of is about 5 eV
27 to about 1,000 eV. The energy range in a further embodiment is about 10 eV to
28 about 500 eV. The energy range in a further embodiment is about 30 eV to about
29 300 eV. In another embodiment, the energy range is in the range of about 60 eV to
30 150 eV. In another embodiment, the energy range is about 140 eV. In an

1 embodiment, the second film has a thickness of greater than 10 microns. In one
2 embodiment, the second film has a thickness in the range of about 10 to 20 microns.
3 In one embodiment, the second film has a thickness in the range of about 1 to 5
4 microns.

The paragraph beginning at page 30, line 5, is amended as follows:

5 An electrolyte third film, e.g., films 61, 61C or 73, having ionic transport
6 qualities but not being electrically conductive (an electrolyte) is deposited so as to
7 completely overlay the second deposited film. In one embodiment, the third film is
8 deposited using a first deposition source and a secondary source supplying energetic
9 ions to the growing film. In some embodiments, the first deposition source is a
10 physical vapor deposition source. In some embodiments, the secondary source is an
11 ion source with the capability of supplying energetic ions having an energy greater
12 than 5 eV. In another embodiment, the energy range is about 5 eV to about 3,000 eV.
13 In one embodiment, the energy range of is about 5 eV to about 1,000 eV. The energy
14 range in a further embodiment is about 10 eV to about 500 eV. The energy range in
15 a further embodiment is about 30 eV to about 300 eV. In another embodiment, the
16 energy range is in the range of about 60 eV to 150 eV. In another embodiment, the
17 energy of the ions from the secondary source is about 140 eV. In some
18 embodiments, the secondary source includes oxygen (e.g., ~~O₂~~ O₂) or nitrogen (e.g., ~~N₂~~ N₂)
19 gas. The secondary source gas, in another embodiment, includes a noble gas, e.g.,
20 argon, xenon, helium, neon, and krypton. The secondary source gas, in another
21 embodiment, includes a hydrocarbon material such as a hydrocarbon precursor.
22 Selection of the secondary source gas is based on the desired effect on the
23 stoichiometry of the deposited film. The secondary source, in one embodiment,
24 provides a focused beam of energized ions. The secondary source, in one
25 embodiment, provides a non-focused beam of energized ions. It is desirable to
26 make the electrolyte, third layer as thin as possible and prevent the cathode and
27 anode layers from shorting. In an embodiment, the third film has a thickness of less
28 than 1 micron. In one embodiment, the third film has a thickness in of less than
29 5,000 Angstroms. In another embodiment, the third film has a thickness of less than

1 1,000 Angstroms. In another embodiment, the third film has a range of about 10
2 Angstroms to about 100 Angstroms.

The paragraph beginning at page 31, line 9, is amended as follows:

9 An anode, fourth film, e.g., film 65 or 75 includes from a lithium-
10 intercalation material that is deposited on and overlays the third film but not
11 contacting first film (barrier) or second film (cathode). In one embodiment, the
12 fourth film is deposited using a first deposition source simultaneously with a
13 secondary source supplying energetic ions to the growing fourth film. In some
14 embodiments, first deposition source is a physical vapor deposition source. In some
15 embodiments, the secondary source is an ion source supplying energetic ions from a
16 source gas that includes oxygen (e.g., O_2 O_2) or nitrogen (e.g., N_2 N_2). The source gas,
17 in another embodiment, includes a noble gas, e.g., argon, xenon, helium, neon, and
18 krypton. The source gas, in another embodiment, includes a hydrocarbon material
19 such as a hydrocarbon precursor. Selection of the secondary source gas is based on
20 the desired effect on the stoichiometry of the deposited film. The secondary source,
21 in one embodiment, provides a focused beam of energized ions. The secondary
22 source, in another embodiment, provides an unfocused beam of energized ions. The
23 energized ions provide energy to the lithium-intercalation material in the range of
24 about 5 eV to about 3,000 eV. In one embodiment, the energy range of is about 5
25 eV to about 1,000 eV. The energy range in a further embodiment is about 10 eV to
26 about 500 eV. The energy range in a further embodiment is about 30 eV to about 00
27 eV. In another embodiment, the energy range is in the range of about 60 eV to 150
28 eV. In another embodiment, the energy range of the ions from the secondary source
29 is about 140 eV. In an embodiment, the fourth film has a thickness of greater than

1 10 microns. In one embodiment, the fourth film has a thickness in the range of
2 about 10 to 40 microns.

The paragraph beginning at page 35, line 22, is amended as follows:

22 In some embodiments, the materials and compositions of photovoltaic cell
23 800 are conventional CdS/CdTe materials such as is described in U.S. Patent No.
24 4,207,119, which is incorporated by reference; with the additional processing
25 according to the present invention to anneal or treat the surface (e.g., by ion-assist
26 beam) of the films as they are deposited~~using~~. In other embodiments, the
27 compositions used are as described in the following publications, each of which is
28 incorporated by reference: R.W. Birkmire et al, "Polycrystalline Thin Film Solar
29 Cells: Present Status and Future Potential," Annu. Rev. Mater. Sci. 1997.27:625-653
30 (1997); T.L. Chu et al, "13.4% Efficient thin-film CdS/CdTe Solar Cells," J. Appl.

1 Phys. 70 (12) (15th December 1991); T. Yoshida, "Photovoltaic Properties of
2 Screen-Printed CdTe/CdS Solar Cells on Indium-Tin-Oxide Coated Glass
3 Substrates," J. Electrochem. Soc., Vol. 142, No. 9, (September 1995); T. Aramoto
4 et al., "16% Efficient Thin-Film CdS/CdTe Solar Cells," Jpn. J. Appl. Phys. Vol. 36
5 pp 6304-6305 (Oct. 1997); R.B. King, ed. "Encyclopedia of Inorganic Chemistry"
6 Vol 3., pp 1556-1602, John Wiley & Sons Ltd., (1994).

The paragraph beginning at page 36, line 12, is amended as follows:

12 In a heterojunction photovoltaic cell, the semiconductor films are formed of
13 different materials. For a rectifying junction, the semiconductor films must also be
14 of different type, that is p or n type. The junction between the two semiconductor
15 films is both a pn junction and a heterojunction. The first semiconductor film on
16 which solar light is incident has a band gap higher than that of the second
17 semiconductor film. The band gap of a semiconductor is the energy separation
18 between the semiconductor valance band and the conduction band. The band gap of
19 this first semiconductor film is chosen so that it corresponds to light in the short
20 wavelength region of the solar spectrum. Photons of light having energy equal to or
21 greater than the band gap of the first semiconductor film are strongly absorbed, but
22 photons of light of energy less than the band gap of the first semiconductor pass
23 through the first semiconductor and enter the second semiconductor film. Examples
24 of materials used for the first semiconductor film include CdS, ZnS, CdZnS, CdO,
25 ZnO, CdZnO, or other wide band gap semiconductors like SiC, GaN, InGaN, and
26 AlGaN. The second semiconductor film is chosen from materials that have band
27 gaps that correspond well to the long wavelength onset of solar radiation. Materials
28 such as CdTe, ~~CuInSe₂~~ CuInSe₂, InP, GaAs, InGaAs, InGaP, and Si are examples of
29 materials for the second semiconductor film.

The paragraph beginning at page 56, line 9, is amended as follows:

9 Figure 15H shows that the batteries have been folded along the fold lines to
10 form a stack of three batteries ~~1100~~, 1110, 1110' and 1110". The folds shown in
11 Figure 15H are a fan fold. Once the fan fold is formed, as shown in Figure 15H, the
12 fan folded battery, including three cells 1330, can be formed in any desired shape,
13 such as ~~those shown in~~ square-sided shape 1503 of Figure 15C, angle-sided shape
1504 of 15D and curve-sided shape 1505 of 15E. The three-celled or multi-celled
14 unit 1330 can be adhered to the interior or exterior surface of any electronic device,
15 as discussed above. It should be noted that the fan fold can include more than three
16 batteries or less than three batteries. The inventive aspect is that it includes a
17 plurality of batteries. The cells 1110, 1110' and 1110" can be attached to one
18 another so that the cells are in series after they are diced. Another possibility is that
19 the electrical contacts for each of these could be put in contact with one another as a
20 result of fan folding the multi-celled unit 1330.

The paragraph beginning at page 56, line 21, is amended as follows:

21 Figures 15I, 15J and 15K show yet another embodiment of the invention. In
22 this particular embodiment of the invention, the sheet of electrical cells 1300
23 includes a plurality of cells including 1110 and 1110'. The entire sheet 1300 is then
24 vacuum formed to form more or less an egg carton 1350 with individual battery
25 cells 1110 and 1110' being formed within well 1360 and 1362 in the sheet 1300.
26 Between the wells 1360 and 1362 is a living hinge 1370. The batteries 1110 and
27 1110' are at the bottom of each well ~~1160 and 1162~~ 1360 and 1362, as shown in Figure 15K. The
28 living hinge 1370 is positioned between the two wells 1360 and 1362. The first cell
29 1360 can be folded on top of the second well 1362 to form an electronic device
30 enclosure 1380, as shown in Figure 15L. It should be noted that the size of the

1 battery portions 1110 and 1110' can be limited or placed so that other traces and
2 room for other electronic devices can be added so that a total circuit can be formed
3 within a disc enclosure. This provides for an advantage that wherein the electronic
4 component could be directly placed into the wells 1160 and 1162 at sites formed at
5 the same time as the batteries were deposited onto the sheet 1300. After placing all
6 the various electronics, the electronic device can be formed merely by dicing two of
7 the wells 1360 and 1362 so that they form a top and bottom of the device enclosure
8 1380. All sorts of electronic devices could be included, including an LCD or other
9 display device. The LCD may be readable directly through a sheet if it is
10 transparent or the sheet, or one of the wells 1360 and 1362, may be provided with an
11 opening that would correspond to an opening or face of the display of an LCD or
12 other display device. Thus, the sheet and the deposited battery thereon can
13 ultimately become the exterior surface or the enclosure for the device formed on the
14 sheet. This has a great advantage in that the process steps necessary to form a
15 device are or can be quite easily and efficiently done in a continuous process. This
16 would lead to very efficient manufacturing of electronic devices.

The paragraph beginning at page 57, line 17, is amended as follows:

17 Figure 16A is a plan view of a sheet including a plurality of cells 1110
18 according to this invention. Figure 16A, 16B and 16C show a way to form a
19 laminated battery cell and possibly laminated battery cell and electronics for a smart
20 card or other invention that includes a battery and electronics within a card. The
21 sheet 1300 shown in Figure 16A includes cells 1110. The sheet also includes fold
22 lines 1390 and 1392. The sheet 1300 is diced into individual sections, which
23 include fold lines 1390 and 1392, as well as a battery cell site 1110. The battery cell
24 site might also include electronics that are also deposited with the battery or energy
25 source onto the sheet 1300. The diced portion 1400 includes one portion including
26 the cell 1100 and two blank portions 1402 and 1403. The diced portion 1400 is then
27 fan folded, as shown in Figure 16C. Once a fan fold has been formed, the cell
28 portion 1110 is captured between the two unpopulated sheet portions 1402 and 1403
29 and will provide an extra protective layer. The excess portions of the sheet 1300

1 can be trimmed, as shown in Figure 16D to produce a smart card or card including
2 both a battery 1110 and electronic, as shown as item 1600E in Figure 16E.

The paragraph beginning at page 58, line 3, is amended as follows:

3 Figure 17 is an exploded perspective view of a diced portion of a sheet 1300
4 which includes one battery cell 1110 rolled around an electrical motor 1500. In this
5 case, the diced portion ~~1300~~, which includes a cell 1110, is an elongated strip 1510
6 from the original sheet 1300. The elongated strip 1510 may include several
7 batteries placed in series or one elongated battery that is laid down as a strip on the
8 sheet 1300. The electrical motor is electrically connected to the anode and cathode
9 of the battery and then rolled on to the electrical motor 1500. In this case, the strip
10 1510, on which the battery has been deposited, becomes the case for the electrical
11 motor or also can be viewed as being a part of the case of the electrical motor. The
12 electrical motor can be provided with a sprocket 1520 that is used to drive another
13 gear 1530 having a shaft 1532 attached thereto. As shown in Figure 17, a chuck
14 1540 is placed upon the shaft 1532 to form a drill or other power tool.
15 Advantageously, the power tool could be light and compact, as well as being
16 capable of being recharged a multiplicity of times. The power tool could be a
17 hand held drill for homeowner use or a smaller device, such as a Dremel-brand
18 rotary hand tool.

The paragraph beginning at page 59, line 4, is amended as follows:

4 Figures 18C and 18D show another embodiment of the invention for a
5 lighting device. In this particular embodiment, again a strip 1600 is provided with a
6 switch 1602 and an LED 1604. In this particular embodiment, the LED is
7 positioned so that it extends beyond the length of the sheet 1600. In this particular
8 embodiment, the sheet 1600 is rolled along its longer dimension around the LED
9 1604 to form an elongated case having the LED 1604 at one end of the case and a
10 switch 1602 at the other end of the case. This forms a light emitting diode light
11 1630 in which the ~~dice~~ sheet 1600 is part of the case.

The paragraph beginning at page 60, line 27, is amended as follows:

27 A second process is shown in Figure 21B. The second process shown in
28 Figure ~~19B~~ 21B is useful for devices in which the battery 1110 may be removed easily
29 from the enclosure portion. As before, the first step, depicted by reference numeral
30 1930, is to determine if the electronics are obsolete. If they are, the battery 1110 is

1 merely removed from the case for the enclosure portion and recycled for use in
2 another enclosure portion having a similar contour, as depicted by reference
3 numeral 1950.

The paragraph beginning at page 64, line 9, is amended as follows:

9 Figure 22G shows a block diagram perspective view of an integrated device
10 ~~2207~~ 2203 implementing circuit 2200 of Figure 22A having the battery 2320 and the
11 circuit 2330 built side-by-side on a substrate 2310. In some embodiments, a pattern
12 of conductive areas or traces is deposited on substrate 2310, and the successive
13 layer(s) of battery 2320 and circuit 2330 are then deposited. In some embodiments,
14 circuit 2330 consists only of these conductive traces. In other embodiments, one or
15 more of the process steps or deposited layers of battery 2320 and circuit 2330 are
16 common, and thus performed at substantially the same time for both circuit 2330
17 and battery 2320, thus increasing the reliability, speed and yield of fabrication and
18 lowering the cost of fabrication. In the embodiment shown, trace 2318 is deposited
19 on substrate 2310 and forms a common bottom electrical connection for both circuit
20 2330 and battery 2320. Other aspects of Figure 22G can be understood by reference
21 to Figures 22A-22C.

The paragraph beginning at page 66, line 1, is amended as follows:

1 Figure 24A shows a perspective view of an embodiment 2400 of the present
2 invention having a battery 2320 overlaid with an integrated device 2430. In some
3 embodiments, integrated device ~~2340~~ 2430 is a so-called supercapacitor relying on either
4 charge accumulation on opposing sides on an insulator (as in a capacitor) or ion
5 transport across an electrolyte (as in a battery), or both charge accumulation and ion
6 transport to store electrical energy. In some embodiments, integrated device ~~2340~~ 2430
7 includes a photovoltaic cell of conventional construction deposited directly on
8 battery 2320.

The paragraph beginning at page 66, line 9, is amended as follows:

9 Some embodiments further include a separately fabricated circuit device
10 such as an integrated circuit chip 2440 that is wire-lead bonded to device 2430 using
11 wire 2441, to device-battery common terminal 2324 using wire 2443, and to bottom
12 battery contact 2322 using wire 2442. For example, in one embodiment having a
13 supercapacitor device 2430, integrated circuit ~~2430~~ 2440 includes a wireless
14 communication circuit that uses the battery for overall power needs and uses
15 supercapacitor device 2430 for quick-burst power needs such as for transmitting
16 short burst of data to an antenna. Other embodiments include other fabricated
17 circuit devices such as switches, LEDs or other light sources, LCD displays,
18 antennas, sensors, capacitors, resistors, etc., wired to device 2400.

The paragraph beginning at page 71, line 15, is amended as follows:

15 Figures 25B-25E show a fabrication sequence for cofabrication of solid-state
16 integrated circuits and solid-state energy source such as that described above, but
17 onto a packaged IC 2540. Figure 25B shows a plan view and Figure 25C shows an
18 elevational view of IC 2540. In some embodiments, IC 2540 includes a silicon chip
19 2545 having integrated components such as transistors, resistors, memory, etc., a
20 lower substrate ~~2540~~ 2546, and a wiring superstrate 2544 having deposited wires ~~2540~~ 2543
21 that extend to bonding vias 2542. Figure 25D shows a plan view and Figure 25E
22 shows an elevational view of an integrated battery-IC 2501. Battery-IC 2501
23 includes a cathode 2326 (e.g., lithium cobalt oxide), electrolyte layer 2327 (e.g.,
24 LiPON), and anode layer 2328 (e.g., including copper, carbon, lithium, lithium-
25 magnesium, and/or other suitable anode material). Passivation overcoat layer 2329
26 suitable to protect the inner components of battery 2320 is then deposited or grown.

The paragraph beginning at page 71, line 27, is amended as follows:

27 In one embodiment, the ~~product~~ packaged IC 2540 product is formed by conventional
28 means. All machine work and cleaning is accomplished. The package 2540 is sent
29 to energy processing for deposition of battery 2320 or other energy-storage device.
30 The design of the package included a suitable area 2549 for deposition of battery

1 components. Using shadow masks with sufficient overlay accuracy, the necessary
2 components of the energy structure (e.g., a battery and/or photovoltaic cell) are
3 deposited using the methods described above. A final passivation coating 2329 is
4 applied to the energy stack structure. The package with energy structure integrated
5 is sent for assembly.

The paragraph beginning at page 72, line 24, is amended as follows:

24 Figure 25F shows a block diagram of a layer-deposition system 2560 much
25 the same as that of Figure 24B, however rather than using a sheet of polymer or
26 other homogenous substrate material 2410, system 2560 starts with a sheet 2561
27 having a plurality of processed ~~circuits~~ packaged ICs 2540 that are received by takeup reel 2563.

The paragraph beginning at page 73, line 3, is amended as follows:

3 Figure 26A shows a perspective view of an device 2600 of the present
4 invention having an integrated circuit 2510 overlaid on its back with a battery 2320.
5 This embodiment is similar to that of Figure 25A, except that the battery 2320 is
6 deposited on the back of IC 2510, and is wire-lead bonded to contact 2514 using
7 wire 2614 from battery contact 2519 and to contact 2515 using wire 2615 from battery contact 2518.

The paragraph beginning at page 73, line 29, is amended as follows:

29 In some embodiments, embodiment 2600 further includes an antenna or
30 electromagnetic radiation receiving loop ~~2660~~ 2662 fabricated on a surface of integrated

1 circuit 2510, for example, on the opposite side as that facing battery 2320. In some
2 such embodiments, device 2600 also includes one or more devices 2650 such as
3 sound transducers for such applications as a hearing aid having ~~an~~ a combined
4 transducer-battery-amplifier device in order to provide a radio frequency-wave-
5 rechargeable hearing aid which could be taken out of the ear at night and placed in an
6 RF-emitting recharging stand (e.g., that of Figure 27M), avoiding the need to
7 replace batteries or even to electrically connect to an external recharging circuit.

The paragraph beginning at page 74, line 8, is amended as follows:

8 In various embodiments, such an antenna or electromagnetic radiation
9 receiving loop ~~2660~~ 2662 is fabricated on device 2202, 2203, ~~2203~~, 2204, 2206, 2207,
10 2208, 2300, 2400, or 2500 (or 2700 described below) or other battery devices
11 described herein. In some such embodiments, electromagnetic radiation received
12 wirelessly by antenna ~~2660~~ 2662 can be such low-frequency radiation as 50- or 60-hertz
13 magnetic radiation from a coil connected to house current (e.g., that of Figure 27L).
14 In other such embodiments, RF radiation such as radio, TV, cellular, etc., having
15 frequencies up to and exceeding 2.4 GHz is received. In some embodiments,
16 multiple antennae are used, e.g., one for transducing communications signals and
17 another for receiving recharging signals.

The paragraph beginning at page 77, line 3, is amended as follows:

3 Figure 27L shows an perspective view of a device 2700 of Figure 27E, but
4 further including a photovoltaic cell 2650, at a light-recharging station that includes
5 lamp 2791. In some embodiments, device 2700 is fabricated in a shape to fit in the ear,
6 includes sound transducers, and functions as a hearing aid that can be recharged an
7 indefinite number of times, eliminating the need to replace its battery.

The paragraph beginning at page 77, line 13, is amended as follows:

13 Solid-state rechargeable batteries such as those described above have the
14 unique ability of being integrated directly with the electronics they will power.
15 Further integration of thin-wire antenna/coil ~~2660~~ 2662 or 2750 to be used as one of the
16 coils of a two-part transformer such as shown in Figure 27K and/or RF-scavenging
17 technology such as that used in keyless entry systems allows the recharging of the
18 solid-state thin-film battery 2320 wirelessly (through the air). Using techniques
19 already common in RF I.D. tagging, the communicated energy is converted into a
20 D.C. voltage and used to perform functions on board. In the case where a battery
21 already exists on board, the D.C. voltage is used to power up recharge circuitry to
22 wirelessly recharge the on-board battery.

The paragraph beginning at page 78, line 27, is amended as follows:

27 Figure 31C shows one method for making a pacemaker 3102. The method
28 includes a plurality of steps carrying the reference numbers 3194, 3195, 3196 and
29 3197. The pacemaker 3102 includes a first half 3131 and a second half 3130. In the
30 initial step, 3194, the second half 3130 is provided. A battery cell 1110 is formed

1 on an interior surface of the pacemaker 3102, as shown by step 3195. The single
2 cell 1110 is deposited on the interior surface, as shown by step 3195. ~~as shown in~~
3 ~~step 3191.~~ The electronics 3150 are then placed onto the battery 1110 to form a
4 circuit with the battery 1110, as depicted by step 3196. The first half 3131 of the
5 enclosure is placed over the second half 3130 to form the assembled pacemaker
6 3102, as depicted by step 3197.

The paragraph beginning at page 80, line 22, is amended as follows:

22 Of the 2 billion rechargeable batteries consumed in the United States in
23 1998, only about 300 million were actually recycled. That means about 1.7 billion
24 recyclable batteries made it into landfills. Although more and more of these
25 batteries are technically environmentally safe, this still represents a significant load
26 on the landfill situation in the USA. The present invention provides a solution that
27 will have its greatest impact as solid-state lithium-ion batteries begin to dominate
28 the rechargeable battery market. In this invention, solid-state lithium-ion batteries
29 have a date code and/or recycle value associated with them. Because of the very
30 large (over 40,000) number of charge/discharge cycles possible with solid-state

1 lithium batteries, the average expected life of a cell could exceed 100 years. It is
2 therefore very likely that the product in which the cell is placed will lose its
3 usefulness well before the battery cell is depleted. Thus, when the battery reaches
4 the end of its useful life based on the obsolescence of the product it was in, the
5 consumer will be enticed to recycle the battery based on the value returned to the
6 consumer in exchange for recycling. This value could be a function of the date code
7 and application the battery was used in. The recycler 2810 then disassembles the
8 unit 2800, tests the single cells 2801, and then rebuilds the cells in whatever
9 configuration is most in demand at that time. The rebuilt unit ~~2800~~ could then be
10 sold at an appropriate cost and warranty on performance.

The paragraph beginning at page 82, line 28, is amended as follows:

28 Figure 29A shows a block diagram of a layer-deposition system 2960.
29 System 2960 has layer deposition sections 2962 much the same as those of ~~Figure~~ system
30 2460 of Figure 24B, except that it is set up to deposit layers onto wafers 2961 (or
1 onto diced ICs 2510 rather than onto flexible substrates), resulting in processed wafers 2963. Figure 29B shows a
2 perspective view of a partially processed wafer 2964 having battery material 2320
3 on wafer 2961 or IC 2410.

The paragraph beginning at page 83, line 4, is amended as follows:

4 Figure 29C shows a block diagram of a layer-deposition system 2965.
5 System 2965 has layer deposition sections 2962 much the same as those of ~~Figure~~ system
6 2465 of Figure 24D, except that it is set up to deposit layers onto wafers ~~2964~~ 2966 (or
7 onto diced ICs 2510 rather than onto flexible substrates) by layer-deposition sections
8 2967, resulting in processed wafers 2968. Figure 29D shows a
9 perspective view of a processed sheet 2969 having battery material 2320 on wafer
9 2961 or IC 2410 and covered by a device 2430 such as a photovoltaic cell.

The paragraph beginning at page 83, line 10, is amended as follows:

10 Figure 29E shows a block diagram of a layer-deposition system 2965. In
11 some such embodiments, system 2965 deposits layers forming a photovoltaic cell
12 device 2650 onto a wafer 2971 or IC 2510. Figure 29F shows a perspective view of
13 a partially processed wafer 2974. Figure 29G shows a block diagram of a layer-
14 deposition system 2960. In some such embodiments, system 2960 deposits layers of
15 a battery 2320. Figure 29H shows a perspective view of a processed wafer 2979. In
16 some embodiments, wafer 2979 represents a single device, and in other
17 embodiments, wafer 2979 is diced or cut into a plurality of individual devices and
18 then wired as necessary to connect the signals on the top of the device to the bottom
19 of the device. Figure 29I shows a perspective view of wired diced final device
20 2600 having wires 2914 and 2915.

The paragraph beginning at page 84, line 17, is amended as follows:

17 Figure 31B shows the method for making the pacemaker ~~3100~~ 3101. The method
18 is comprised of a plurality of steps carrying the reference numbers 3190, 3191, 3192
19 and 3193. The pacemaker 3100 includes a first half 3131 and a second half 3130. A
20 plurality of battery cells 1110 are formed on a substrate material 3140, as shown by
21 step 3190. The substrate material 3140 is diced or cut resulting in a single cell 1110
22 on the sheet as diced. The single cell 1110 is adhesively bonded to the second half
23 3130 of the pacemaker 3100, as shown in step 3191. The electronics 3150 are then
24 placed onto the battery 1110 to form a circuit with the battery 1110, as depicted by
25 step 3192. The first half 3131 of the enclosure is placed over the second half 3130
26 to form the assembled pacemaker 3100.